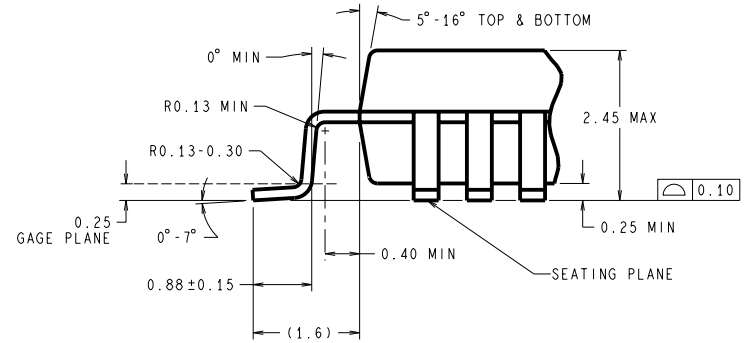
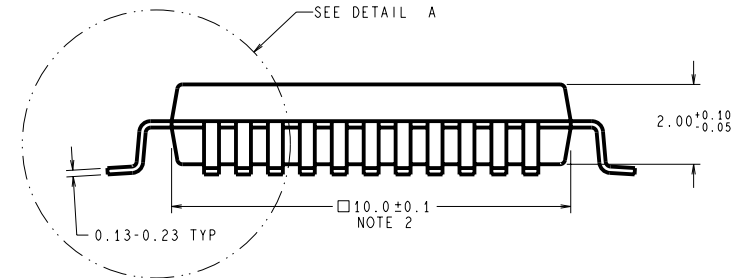
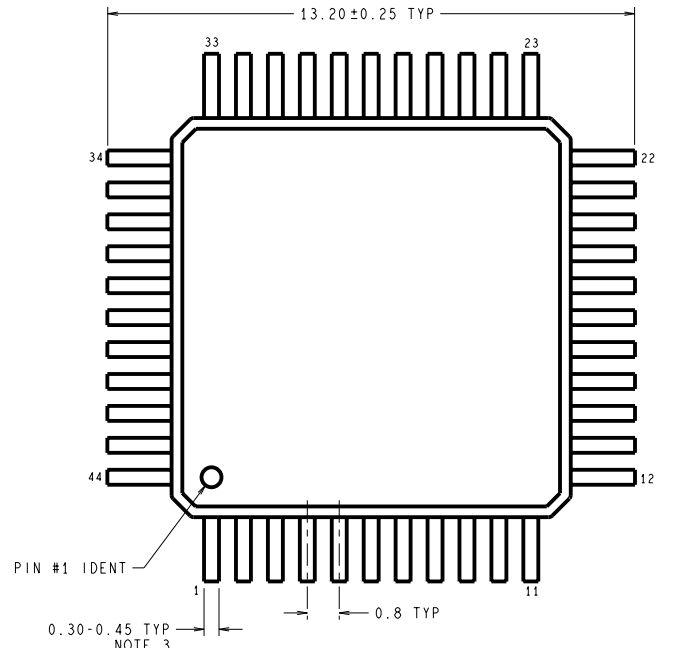


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE AND REDRAW PER ECN.	11035	07/24/95	DEG/



DETAIL A
TYP, SCALE: 20X

DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
 - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
 - DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
ALLOWABLE PROTRUSION SHALL BE 0.15mm.
 - REFERENCE JEDEC REGISTRATION MO-108, VARIATION AA-1,
DATED JAN/94.

APPROVALS	DATE	National Semiconductor			
DRWN <i>D. E. Grady</i>	07/24/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DFTG. CHK.		POFP, JEDEC METRIC, (S), 10 X 10 X 2.0mm, 44 LEAD			
ENGR. CHK.					
		SCALE N/A	SIZE C	DRAWING NUMBER MKT-VGZ44A	REV D
		DO NOT SCALE DRAWING		SHEET 1 of 1	